

**MULTIPLE DIAMOND LAYER
POLYCRYSTALLINE DIAMOND COMPOSITE CUTTERS
AND A METHOD FOR MAKING THE SAME**

Abstract of the Disclosure

An improved polycrystalline diamond composite ("PDC") cutter with at least a secondary PDC cutting surface in addition to a primary PDC cutting surface and a method for making the same, wherein the cutter consists of at least one wafer of cemented tungsten carbide. The secondary cutting surfaces are formed by compacting and sintering diamond on grooves formed at the surface of a wafer forming the cutter body. When more than one wafer is used, the wafers are bonded to form the cutter body. Different grades of diamond may be compacted and sintered in different grooves.

FIGURE 1